

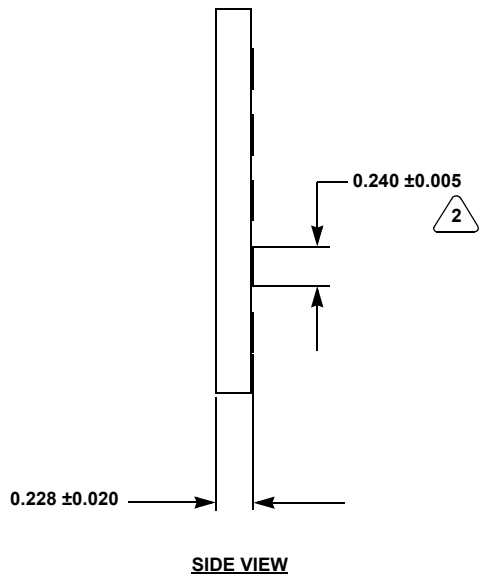
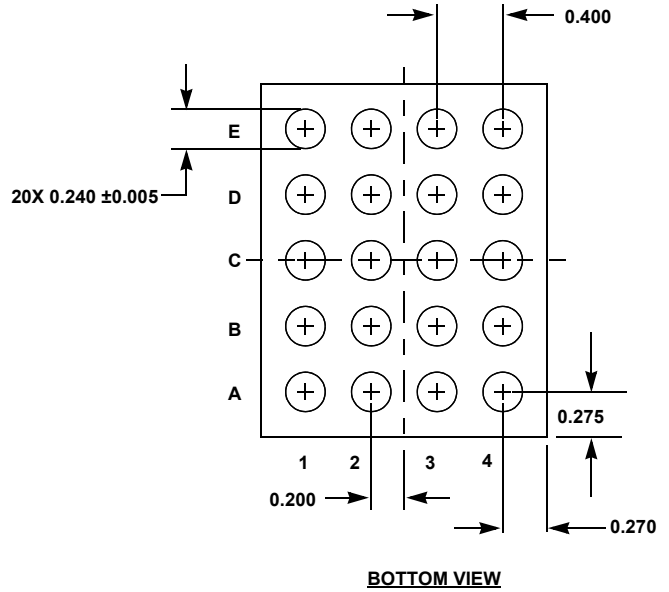
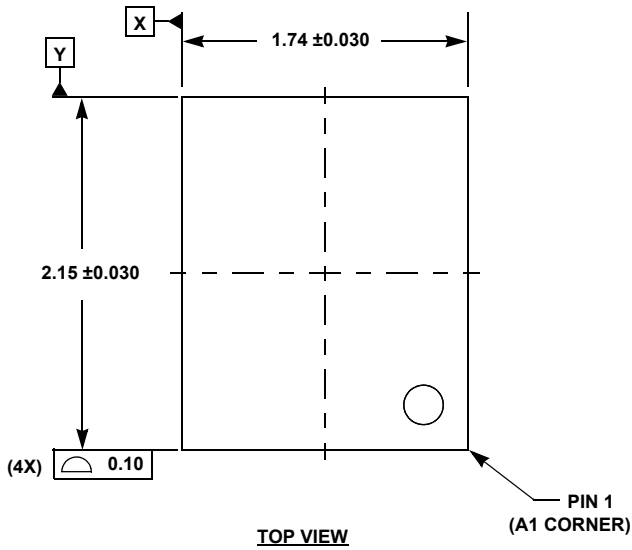
Plastic Packages for Integrated Circuits

Package Outline Drawing

W4x5.20R

20 I/O ULTRA THIN WAFER LEVEL CHIP SCALE PACKAGE (NO SOLDER BALL) WLCSP 0.4mm pitch

Rev 0, 12/16



NOTES:

1. Dimensions and tolerance per ASMEY 14.5 - 1994.
2. I/O position designation per JESD 95-1, SPP-010.
3. All dimensions are in millimeters.